

# New Jersey Semi-Conductor Products, Inc.

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**2N4184 (SILICON)**

## SILICON CONTROLLED RECTIFIER

#### MAXIMUM RATINGS

(Apply over operating temperature range and for all case types unless otherwise noted)

Rating	Symbol	Value	Unit
*Peak Reverse Blocking Voltage (1)	V <sub>RRM</sub>	50	Volts
Forward Current RMS	I <sub>T</sub> (RMS)	8.0	Amp
*Peak Forward Surge Current (One cycle, 60 Hz, T <sub>J</sub> = -40 to +100°C)	I <sub>TSM</sub>	100	Amp
Circuit Fusing Considerations (T <sub>J</sub> = -40 to +100°C; t ≤ 8.3 ms)	I <sup>2</sup> t	40	A <sup>2</sup> s
*Peak Gate Power	P <sub>GM</sub>	5.0	Watt
*Average Gate Power	P <sub>G(AV)</sub>	0.5	Watt
*Peak Gate Current	I <sub>GM</sub>	2.0	Amp
Peak Gate Voltage (2)	V <sub>GM</sub>	10	Volts
*Operating Temperature Range	T <sub>J</sub>	-40 to +100	°C
*Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C
Stud Torque	2N4167-2N4182	15	in. lb.

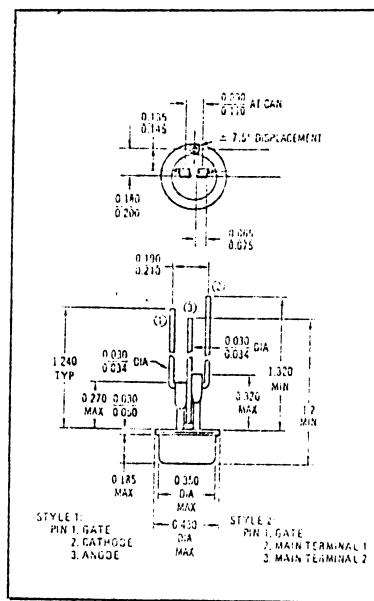
#### **THERMAL CHARACTERISTICS**

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance, Junction to Case (See Fig. 11) 2N4151-66, 2N4183-98	R <sub>θJC</sub>	1.5	2.5*	°C/W
Thermal Resistance, Case to Ambient	R <sub>θCA</sub>	50	—	°C/W

(1) Ratings apply for zero or negative gate voltage. Devices should not be tested for blocking capability in a manner such that the voltage applied exceeds the rated blocking voltage.  
(2) Devices should not be operated with a positive bias applied to the gate concurrently

with a negative potential applied to the anode.

\*Indicates JEDEC Registered Data



ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
*Peak Forward Blocking Voltage (1) ( $T_J = 100^\circ\text{C}$ )	$V_{DRM}$	50	—	—	Volts
*Peak Forward Blocking Current (Rated $V_{DRM} @ T_J = 100^\circ\text{C}$ , gate open)	$I_{DRM}$	—	—	2.0	mA
*Peak Reverse Blocking Current (Rated $V_{DRM} @ T_J = 100^\circ\text{C}$ , gate open)	$I_{RRM}$	—	—	2.0	mA
Gate Trigger Current (Continuous dc) (2) (Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega$ ) *(Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega, T_C = -40^\circ\text{C}$ )	$I_{GT}$	— —	— —	30 60	mA
Gate Trigger Voltage (Continuous dc) (Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega$ ) *(Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega, T_C = -40^\circ\text{C}$ ) *(Anode Voltage = 7.0 Vdc, $R_L = 100 \Omega, T_J = 100^\circ\text{C}$ )	$V_{GT}$	— — 0.2	— —	1.5 2.5 —	Volts
Forward "On" Voltage (pulsed, 1.0 ms max, duty cycle $\leq 1\%$ ) ( $I_F = 15.7 \text{ A}$ )	$V_T$	—	—	2.0	Volts
Holding Current (Anode Voltage = 7.0 Vdc, gate open) *(Anode Voltage = 7.0 Vdc, gate open, $T_C = -40^\circ\text{C}$ )	$I_H$	— —	— —	30 60	mA
Turn-On Time ( $t_d + t_r$ ) ( $I_G = 20 \text{ mA dc}, I_F = 5.0 \text{ A dc}$ )	$t_{on}$	—	1.0	—	$\mu\text{s}$
Turn-Off Time ( $I_F = 5.0 \text{ A dc}, I_R = 5.0 \text{ A dc}$ ) ( $I_F = 5.0 \text{ A dc}, I_R = 5.0 \text{ A dc}, T_J = 100^\circ\text{C}$ ) ( $V_{FXM}$ = rated voltage) ( $dv/dt = 30 \text{ V}/\mu\text{s}$ )	$t_{off}$	— —	15 25	—	$\mu\text{s}$
Forward Voltage Application Rate (Gate open, $T_J = 100^\circ\text{C}$ )	$dv/dt$	—	50	—	$\text{V}/\mu\text{s}$

(1) Ratings apply for zero or negative gate voltage. These devices should not be tested with a constant current source for forward or reverse blocking capability such that the voltage applied exceeds the rated blocking voltage.

(2) For optimum operation, i.e. faster turn on, lower switching losses, best di/dt capability, recommended  $I_{GT} = 200 \text{ mA}$  minimum.

\*Indicates JEDEC Registered Data